

OMB No. 0651-0011 (exp. 4/94)



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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy

1. Name of conveying party(ies):
Kwang-Jin JEONG
Additional name(s) of conveying party(ies) attached? No

2. Name and address of receiving party(ies):
Name: **Samsung SDI Co., Ltd.**
Internal Address:
Street Address: **575, Shin-dong, Yeongtong-gu,**
City: **Suwon-si, Gyeonggi-do 442-731, REPUBLIC OF KOREA**
Additional name(s) & address(es) attached? **No**

3. Nature of conveyance:
 Assignment
 Security Agreement
 Other
Merger
Change of Name
Execution Date: January 9, 2006

112975 U.S. PTO
11/338648
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4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: January 9, 2006
A. Patent Application No.(s)
B. Patent No.(s)
Additional numbers attached? **No**

6. Total number of applications and patents involved: **One**

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: **Eugene M. Lee**
Internal Address: **LEE & MORSE, P.C.**
Street Address: **1101 Wilson Boulevard, Suite 2000**
City: **Arlington**, State: **VA** ZIP: **22209**
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7. Total fee (37 C.F.R. 3.41). \$40.00
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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Eugene M. Lee
Name of Person Signing

Signature
January 25, 2006
Date
Total number of pages including cover sheet, attachmets, and document: **2 pages attached, incl. cover**

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

ASSIGNMENT

Name and Address of Assignee	For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each undersigned inventor has sold and assigned, and by these presents hereby sells and assigns, unto SAMSUNG SDI CO., LTD., 575, Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea
	(hereinafter ASSIGNEE) all right, title and interest for the United States, its territories and possessions in and to his invention relating to

Title of Invention	STRUCTURE FOR HEAT DISSIPATION OF INTEGRATED CIRCUIT CHIP AND DISPLAY MODULE INCLUDING THE SAME as set forth in his United States Patent Application
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Check One	<input type="checkbox"/> executed concurrently herewith <input type="checkbox"/> executed on _____ <input type="checkbox"/> Serial No. _____ Filed _____
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in and to said United States Patent Application including any and all divisions or continuations thereof and in and to any and all Letters Patent of the United States which may issue on any such application or for said invention, including any and all reissues or extensions thereof, to be held and enjoyed by said ASSIGNEE, its successors, legal representatives and assigns to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made;

Each of the undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent to said ASSIGNEE, its successors or assigns in accordance herewith;

Each of the undersigned warrants and covenants that he has the full and unencumbered right to sell and assign the interests herein sold and assigned and that he has not executed and will not execute any document or instrument in conflict herewith;

Each of the undersigned further covenants and agrees he will communicate to said ASSIGNEE, its successors, legal representatives or assigns all information known to him relating to said invention or patent application and that he will execute and deliver any papers, make all rightful oaths, testify in any legal proceedings and perform all other lawful acts deemed necessary or desirable by said ASSIGNEE, its successors, legal representatives or assigns to perfect title to said invention, to said application including divisions and continuations thereof and to any and all Letters Patent which may be granted therefore or thereon, including reissues or extensions, in said ASSIGNEE, its successors, or assigns or to assist said ASSIGNEE, its successors, legal representatives or assigns in obtaining, reissuing or enforcing Letters Patent of the United States for said invention;

Each of the undersigned hereby grants the firm of LEE & MORSE, P.C. the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

NAMES AND SIGNATURES OF INVENTORS		
Name: <i>Kwang-Jin JEONG</i>	Signature: <i>Kwang-Jin JEONG</i>	Date: 9 Jan. 2005
NAMES AND SIGNATURES OF WITNESSES		
Name:	Signature:	Date:
Name:	Signature:	Date:

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